

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PTVS24VS1UR-Q						
		Part Description						
		Nexperia DHAM Protection						
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
	TEST							
	Pre- and Post-Stress Electrical Test	T 1 25.00						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113 Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 125 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	524	22940	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A						
		Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage	1000 hours	205	9400	0		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	156	7080	0		
, , , ,	, , ,	<u> </u>	1000 0,000	150	, 555			
	UHAST	JESD22-A118						
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	156	7080	0		
		JESD22-A102	— 96 Hours					
	AC	Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)						
	HOTER	JESD22-A101						
	H3TRB High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt		rated reverse voltage ^[1]	1000 hours	156	7080	0		
		MIL-STD-750 Method 1037	_30000/3	_55	. 000	-		
	IOL	ton = toff, devices powered to insure ΔTj =						
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
		150000 4444						
	RSH Resistance to Solder Heat	JESD22-A111	10	F.C	1700	•		
# C8	SD Resistance to Solder Heat	200 -C = 3 -C	10 s	56	1700	0		
# C10	Solderability	J-STD-002		56	1700	0		
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^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	9400	0	0,45	2,21E+09

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